



SIDE-EMITTING HIGH HEAT LOAD (HHL) PACKAGE

OVERVIEW

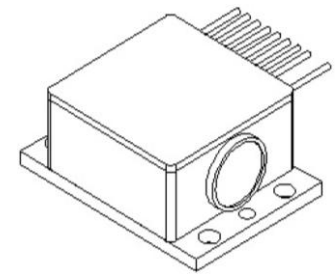
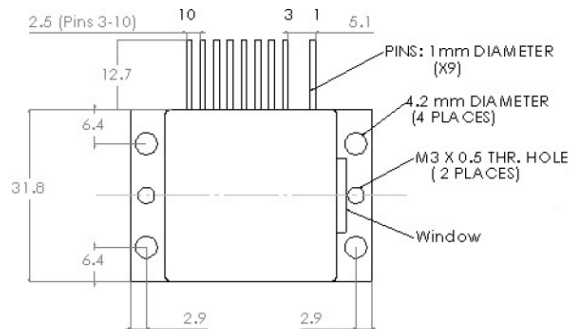
- Pulse or CW operated QCL devices.
- Thermo-electrically cooled. External heat sink still required.
- Sealed in a nitrogen-purged atmosphere.
- Beam Diameter: 3.0 mm to 4.0 mm.

SPECIFICATIONS

Model No		HHL-xx-xx	HHL-xx-xxLP	HHL-xx-xxHP	Units
TEC Parameters (25 °C)	Max. Current	7.9	4.9	4.9	A
	Max. Voltage	14.4	15.2	34.0	V
	Max. Heat Capacity	65.0	67.0	100.0	W
	Typ. Resistance	3.0	3.0	6.0	Ω
Temperature Sensor	Type	RTD 100 Thermal Sensor			----
	Thermistor Constants	$A = 1.129 e^{-3}, B = 2.341 e^{-4}, C = 0.878 e^{-7}$			----
Window	Material	ZnSe			----
	Thickness	1			mm
	Diameter	12.7			mm
	Transmission	> 95			%
Lens	Type	Aspheric			----
	Spectral Range	MWIR to LWIR			----
Weight (approx.)		110.0			g

DIMENSIONS

- Dimension: **mm**
- Linear Vertical Beam Polarization



- Pin 1 - TEC (-)
- Pin 2 - Not Installed
- Pin 3 -
- Pin 4 - Laser (+)
- Pin 5 - Temperature Sensor
- Pin 6 - Temperature Sensor
- Pin 7 - Laser (-)
- Pin 8 -
- Pin 9 -
- Pin 10 - TEC (+)

